engage the bumped contact, the contact comprising a recess in the substrate having a size approximately equal to that of the bumped contact, and a plurality of flexible leads cantilevered over the recess configured to support the bumped contact within the recess and to move within the recess by a distance sufficient to accommodate variations in a size, a shape or a planarity of the bumped contact, each lead having a selected spring constant and at least one projection configured to penetrate the bumped contact.

- 2. (amended) The interconnect of claim 1 further comprising a connecting segment substantially encircling a periphery of the recess configured to electrically connect the leads to one another.
- 5. (amended) The interconnect of claim 1 wherein the recess has four sides and the plurality of leads comprise four leads on the four sides.
- 6. (amended) An interconnect for testing a semiconductor component having a bumped contact comprising:
  - a substrate;
  - a recess in the substrate; and
- a plurality of flexible leads on the substrate cantilevered over the recess configured to electrically engage the bumped contact and to move within the recess by a distance sufficient to accommodate variations in a size, a shape or a planarity of the bumped contact, each lead having a cantilever length, a width, a thickness and a modulus of elasticity selected to provide a desired spring constant, and a shape that substantially matches a topography of the bumped contact.

- 7. (amended) The interconnect of claim 6 wherein each lead includes at least one projection configured to penetrate the bumped contact.
- 8. (amended) The interconnect of claim 6 further comprising a connecting segment on the substrate electrically connecting the leads to one another.
- 9. (amended) The interconnect of claim 6 wherein each lead comprises an enlarged portion on the substrate and a terminal portion cantilevered over the recess for contacting the bumped contact.
- 10. (amended) The interconnect of claim 6 wherein each lead comprises a metal selected from the group consisting of tungsten, titanium, nickel, platinum, iridium, or vanadium.
- 11. (amended) The interconnect of claim 6 wherein the recess has four sides and the plurality of leads comprise four leads on the four sides.
- 12. (amended) An interconnect for testing a semiconductor component having a bumped contact comprising:
  - a substrate;
  - a recess in the substrate; and
- a plurality of leads on the substrate cantilevered over the recess and configured to support and to electrically engage the bumped contact within the recess, and to move in a z-direction within the recess to accommodate variations in a height or a diameter of the bumped contact, each lead having a radius of curvature substantially equal to a radius of the bumped contact.

- 17. (amended) The interconnect of claim 12 wherein each lead has a cantilevered length, a width and a thickness configured to provide a desired spring constant.
- 18. (amended) The interconnect of claim 12 wherein each lead has an enlarged portion on the substrate and a terminal portion cantilevered over the recess for contacting the bumped contact.
- 25. (amended) A system for testing a semiconductor component having a bumped contact comprising:

a carrier for retaining the semiconductor component;

an interconnect on the carrier comprising a substrate, a recess in the substrate having a size approximately equal to that of the bumped contact, and a plurality of leads cantilevered over the recess configured to electrically engage the bumped contact and to move within the recess by a distance sufficient to accommodate variations in a size, a shape or a planarity of the bumped contact, each lead comprising at least one projection configured to penetrate the bumped contact; and

a test circuitry in electrical communication with the leads configured to apply test signals to the component.

- 26. (amended) The system of claim 25 wherein each lead includes a non bonding outer layer and has a radius of curvature substantially equal to a radius of the bumped contact.
- 27. (amended) The system of claim 25 wherein the semiconductor component comprises an element selected from the group consisting of semiconductor dice, semiconductor packages and semiconductor wafers.

- 31. (amended) A system for testing a semiconductor component having a bumped contact comprising:
  - a testing apparatus;
- an interconnect mounted to the testing apparatus comprising:
  - a substrate;
- a recess in the substrate having a size approximately equal to that of the bumped contact; and
- a plurality of leads on the substrate configured to electrically engage the bumped contact, each lead cantilevered over the recess and configured to move within the recess by a distance sufficient to accommodate variations in a size, a shape or a planarity of the bumped contact, each lead having a cantilever length, a width, a thickness and a modulus of elasticity selected to provide a desired spring constant, and a shape substantially matching a topography of the bumped contact; and
- a test circuitry in electrical communication with the connecting segment.
- 32. (amended) The system of claim 31 wherein a connecting segment substantially encircles a periphery of the recess and electrically connects the leads.